



Micro and Nano Systems at LAAS-CNRS: Which Technologies for Today and Tomorrow ?

Anne-Marie Gué, 9 Novembre 2007

Why developing new and innovative technologies ?

Micro and nanotechnologies are a key point for:

- **Health and safety:** early diagnosis, drug discovery, artificial

Biology and health:

monitoring and detection of bio and chemical species
from micro-volumes to single species (molecule, cell, ...)

TICs, ...) and climatic changes

Power management:

Autonomous and energy saving systems,
energy harvesting, energy storage

Communication:

Tele communications, Communicating systems

Technological needs and challenges

The Chinese puzzle !



Complex systems:

- multi functionalities
- multi disciplinary
- heterogeneous (materials)

new structural and functional materials



Nano in Micro:

- Size reduction
- new and revolutionary principles

3D and heterogeneous integration



Various and numerous fields of application:

- large variety of working
- size specification
- cost requirements
- diversification of support or substrate
- ...

nanopatterning:
structural and chemical
patterning

(very) low cost devices: low cost
materials and simplified processes

large area systems, flexible systems



Outline

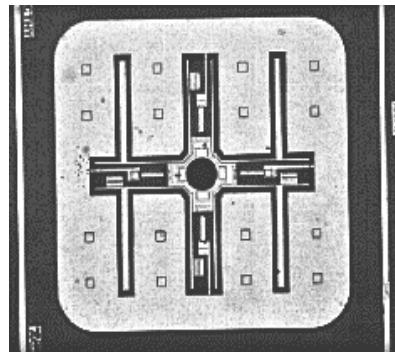
- **From s.c. to multimaterials**
- **From planar technology to 3D and heterogeneous structures**
- **From physics to multidisciplinarity**



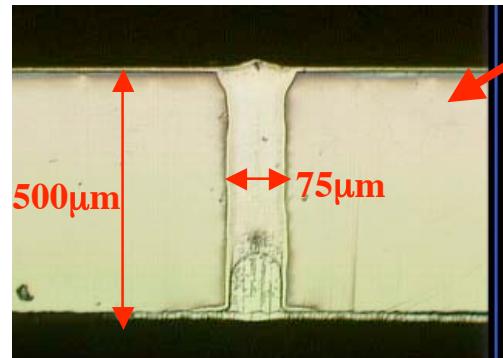
From Planar technology to 3D
and heterogeneous structures

Doubleside process

At the beginning ...

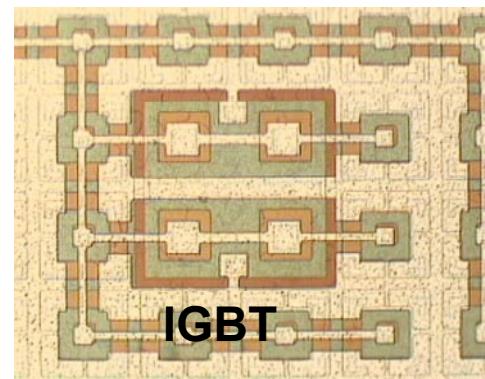
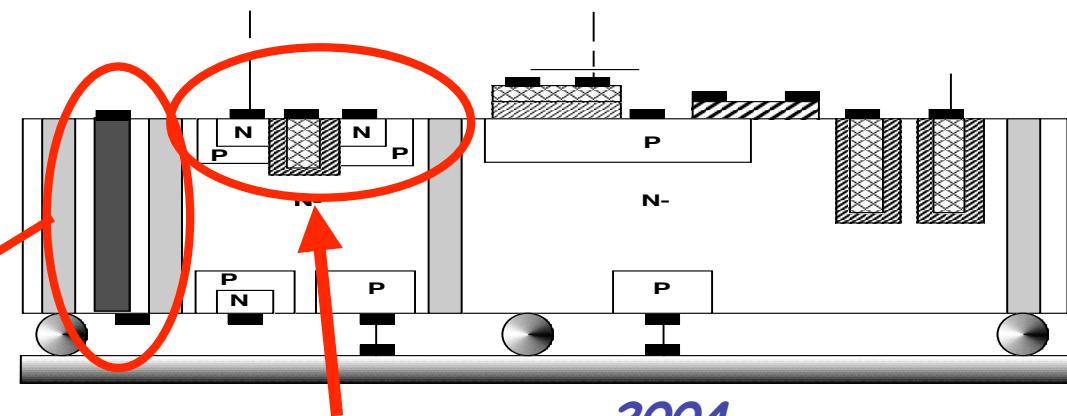


Optically driven thyristor 1980



Thru-wafer vias :

- thru-wafer DRIE
- Al thermomigration
- Specific vertical LPCVD furnace



IGBT

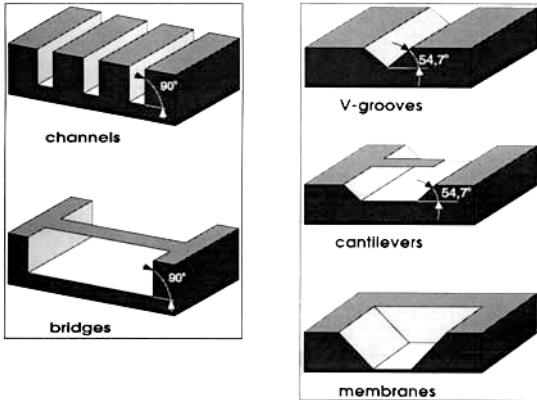


Planar

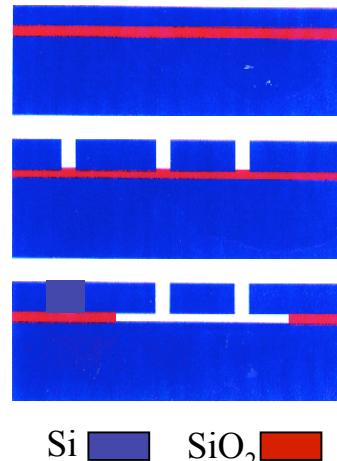
Double side process

3D Si Micromachining

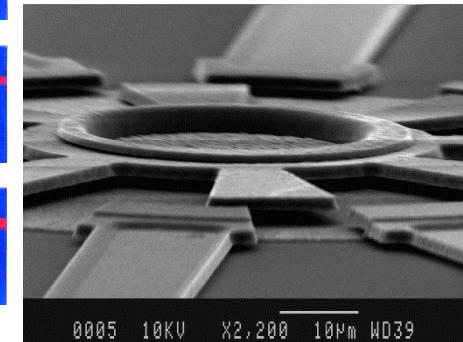
Si wet etching KOH



Si surface micromachining

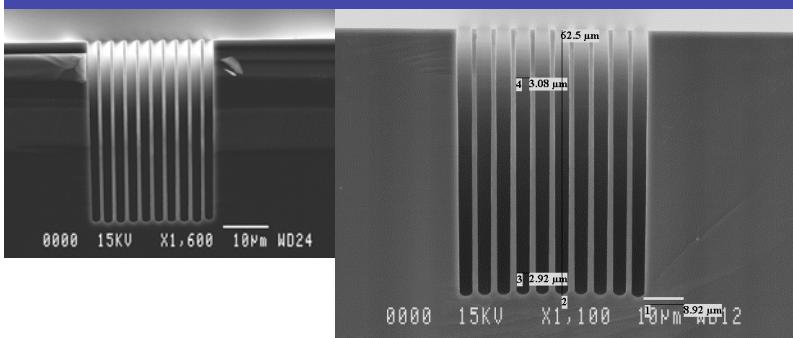


Sacrificial layers:
SOG, SOD, oxidized polySi

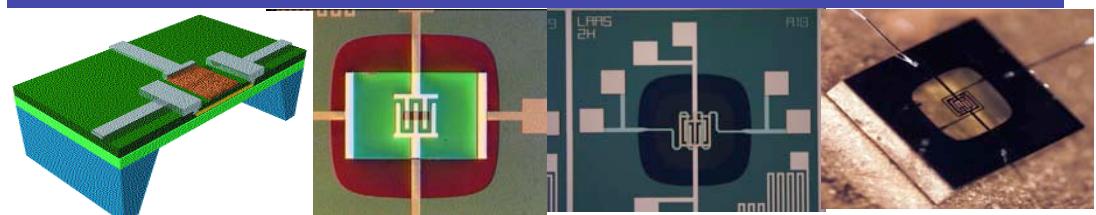


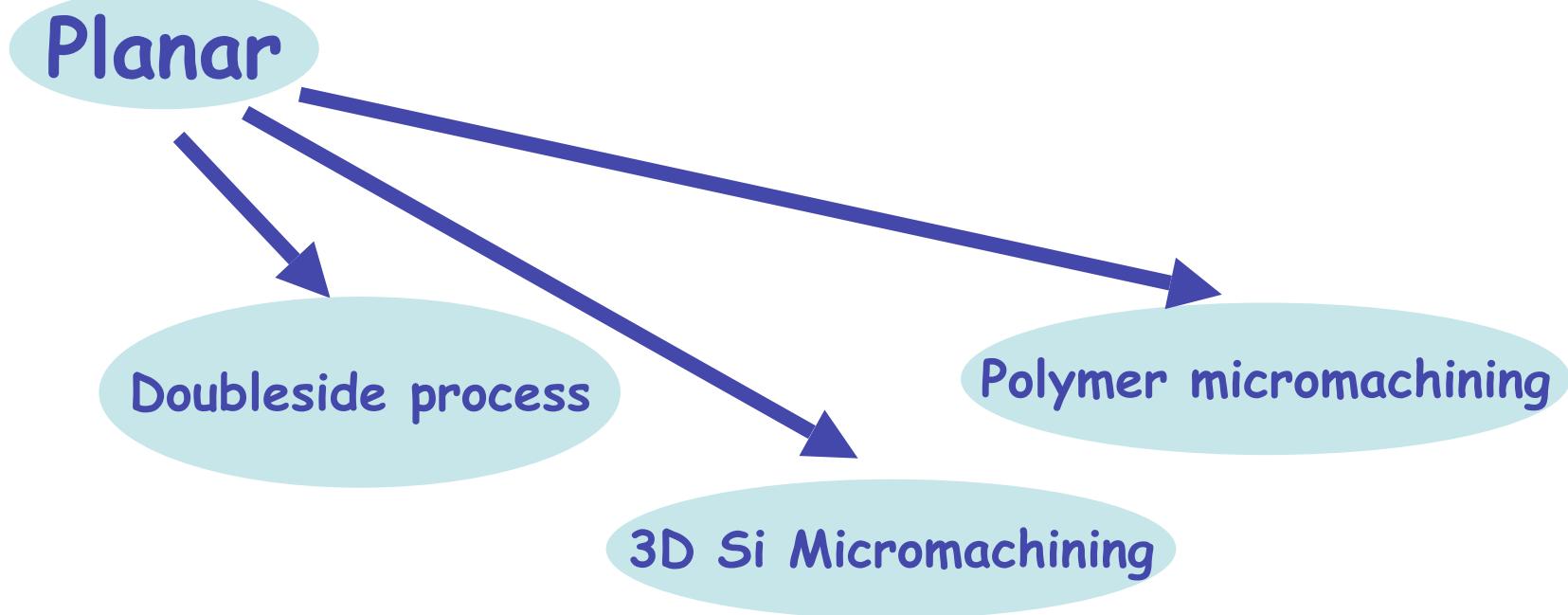
Si SiO₂

Si DRIE for non linear capacitance



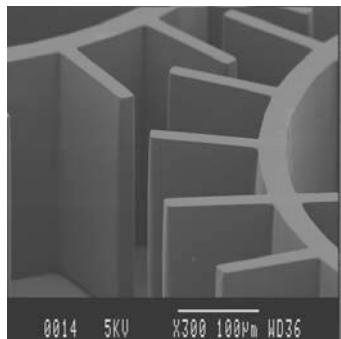
Thin dielectric suspended membranes (hot plates)



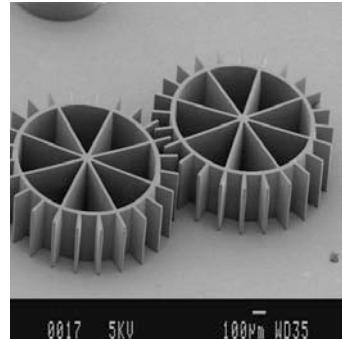


Polymer micromachining: direct lithography

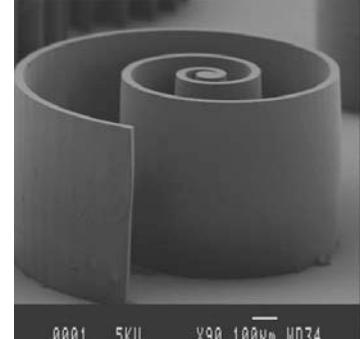
Negative Photoresist (SU 8)



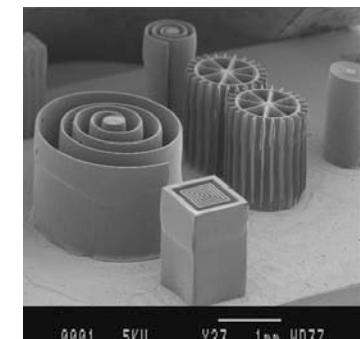
E=200µm



E=300µm

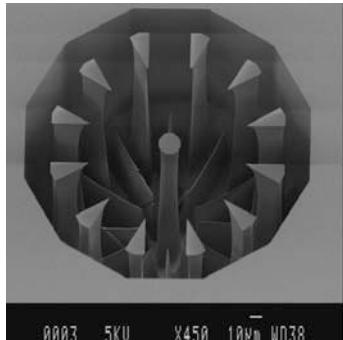


E=500µm

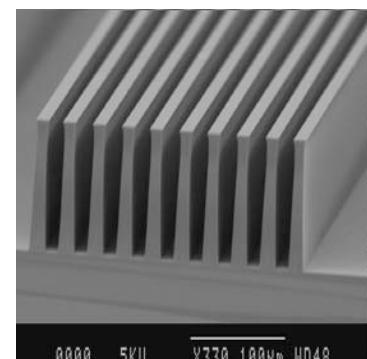


E=1,2mm

Positive Photoresist (AZ 9260)



e=100µm



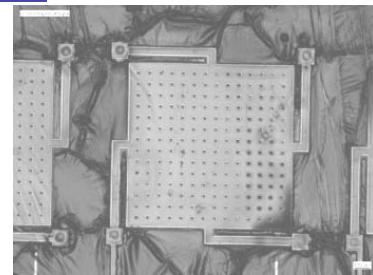
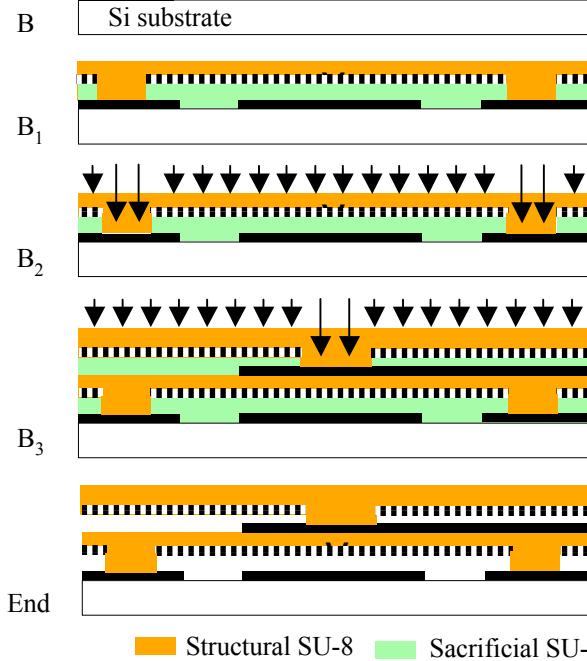
e=100µm

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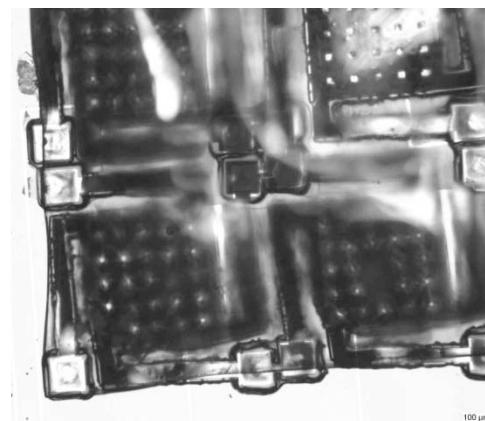
Polymer micromachining: sacrificial layer technology

Adaptative optics

[SU8/SU8]



First level (B₂)



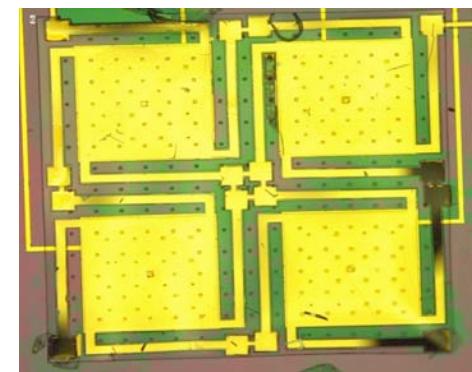
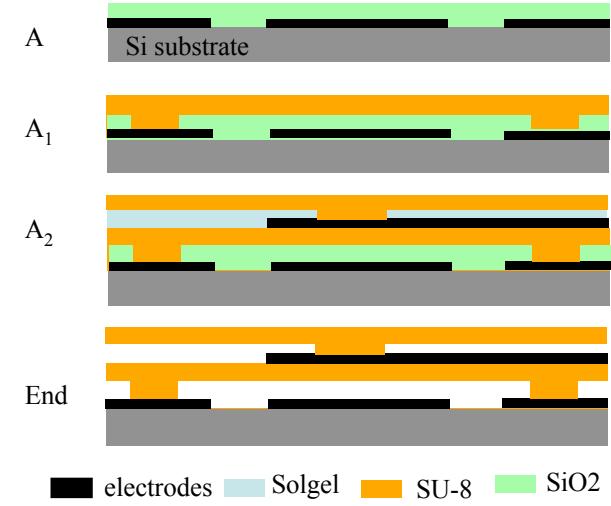
Two levels (end)

Key features

- mirror: roughness < $\lambda/10$
- vertical actuation: up to 10 μm
- pitch: 500 μm to 1 mm

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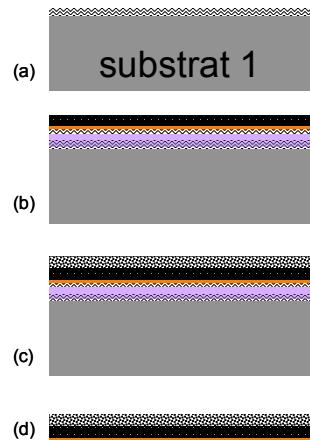
[SiO₂/SU8] + [Solgel/SU8]



Pitch: 500 μm to 1mm

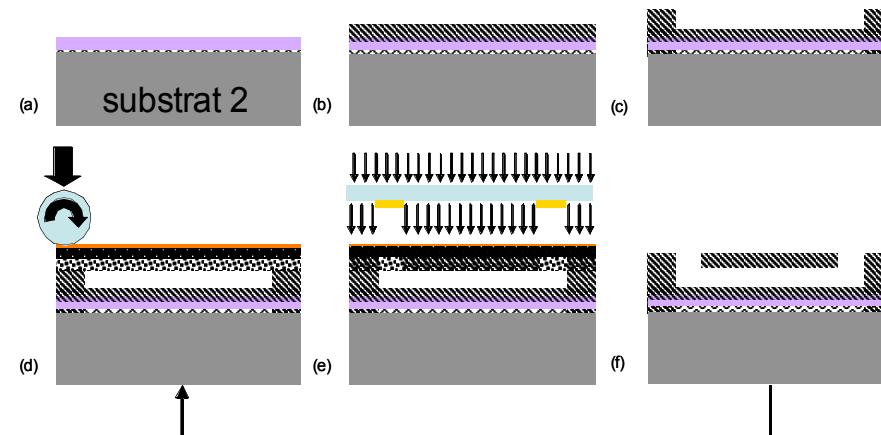
{

Realization of a non crosslinked SU8 flexible film



}

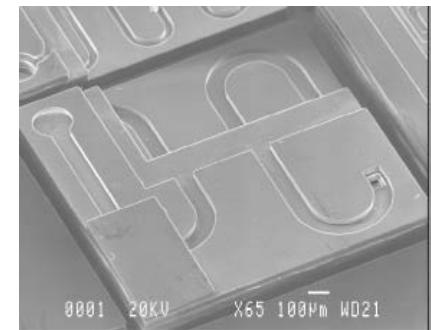
Stacking and patterning of SU8 films



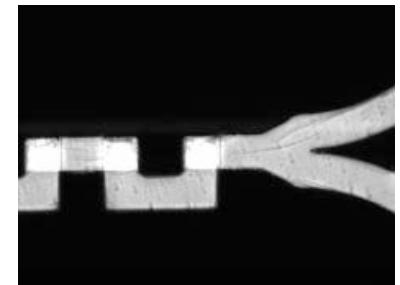
SU-8 non réticulée
 SU-8 réticulée



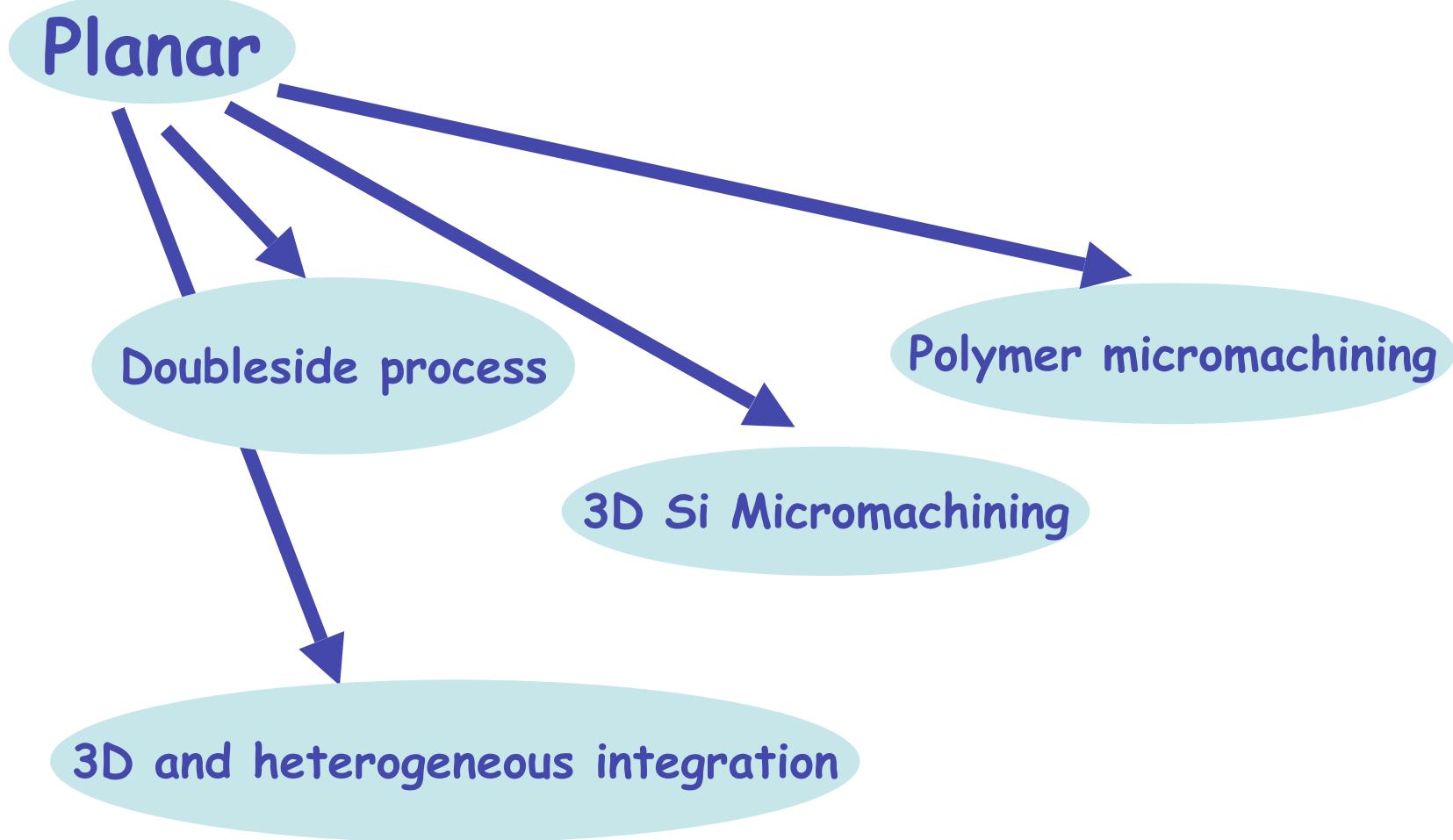
➔ flexible SU-8 chip

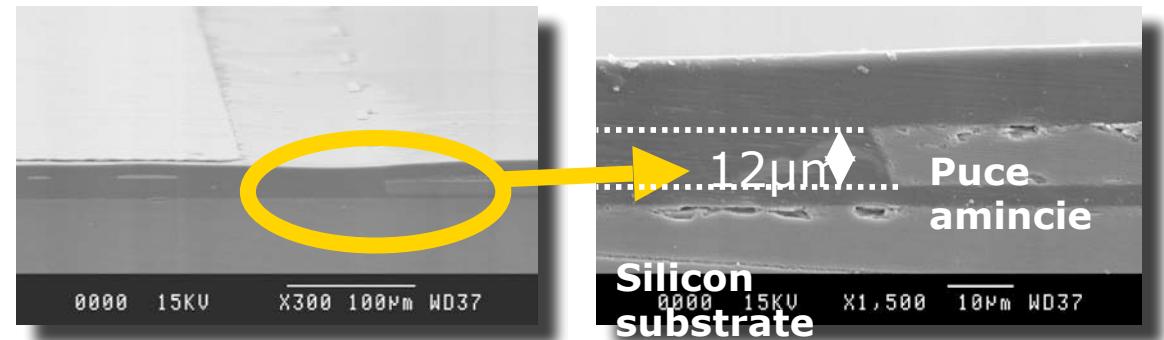
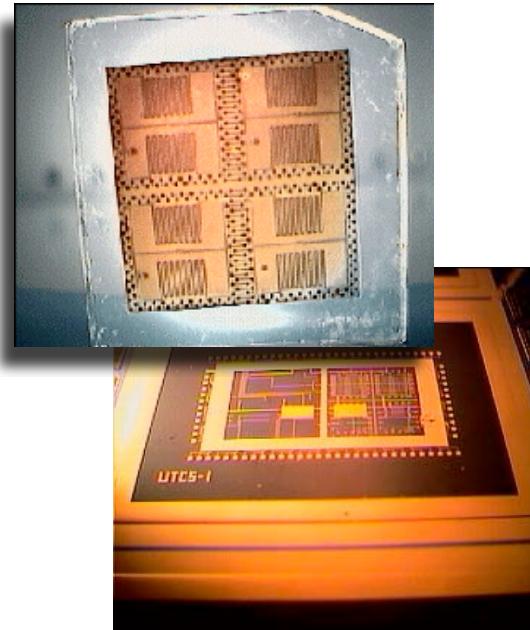
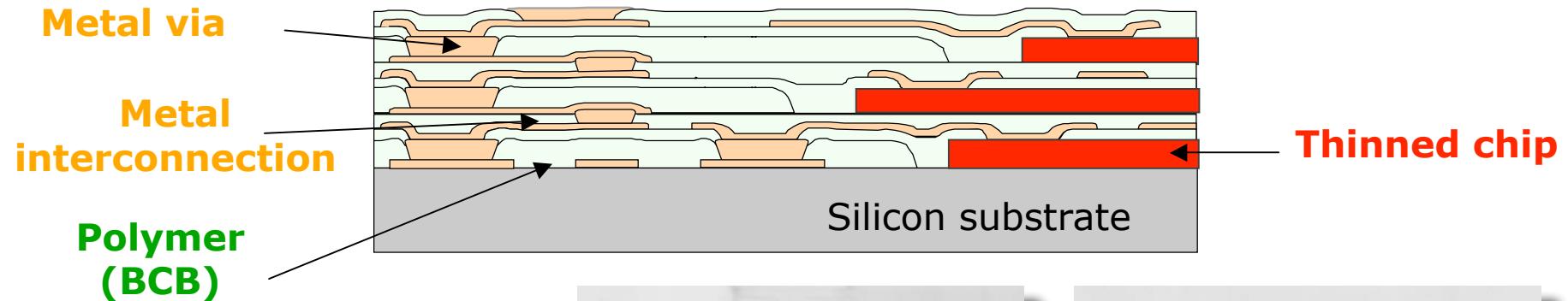


➔ multilevel network



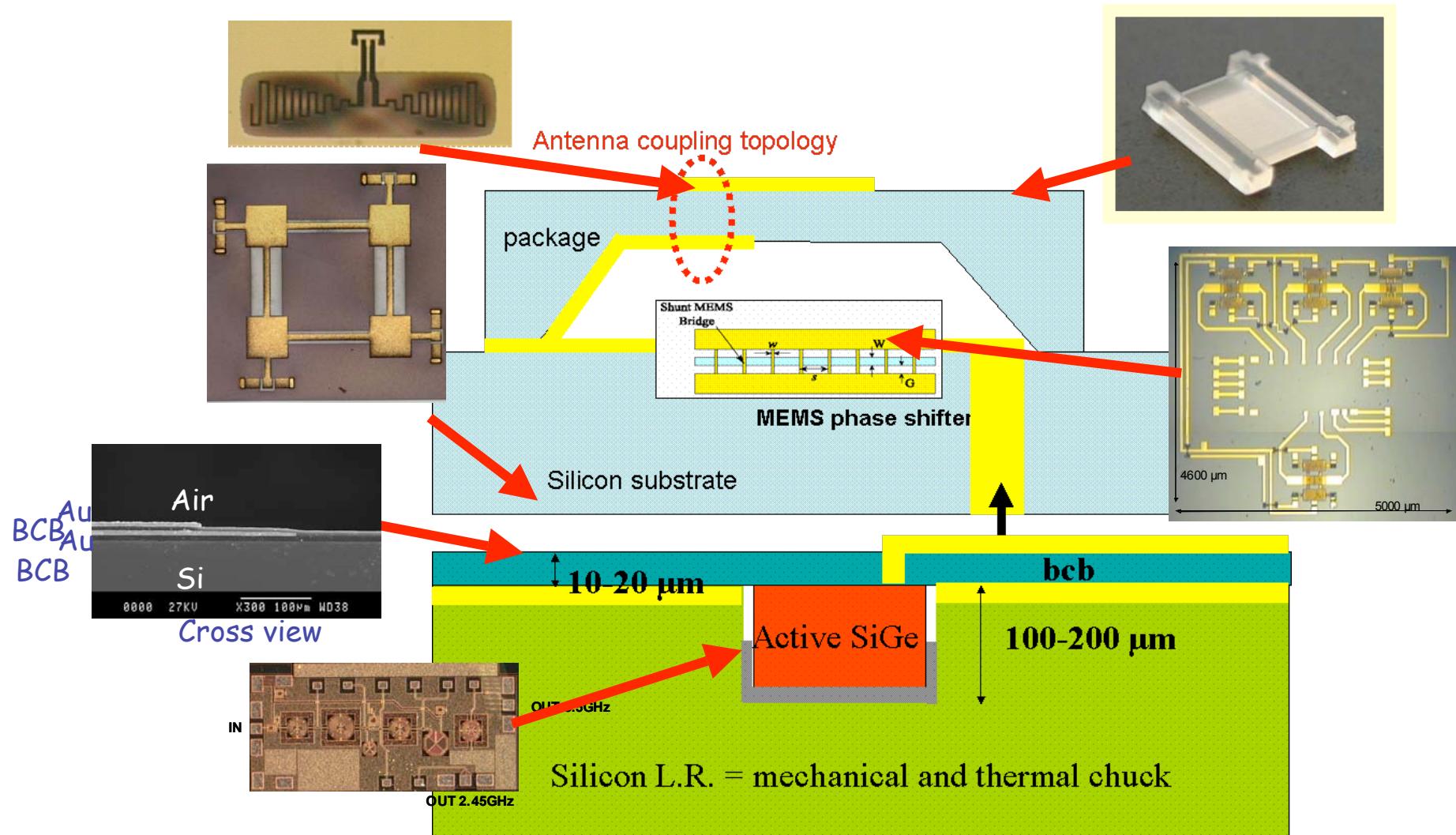
➔ 3D micromixer

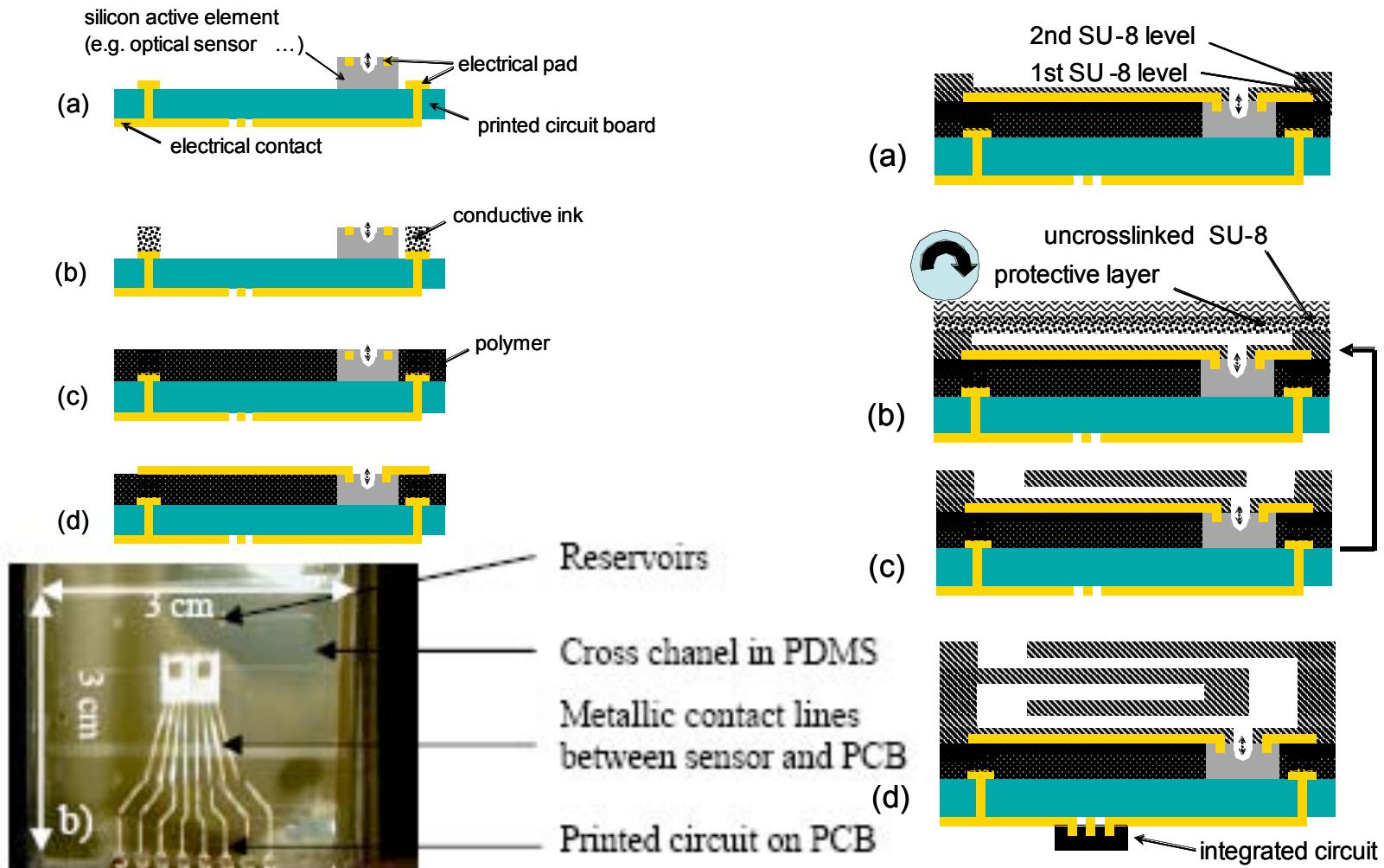


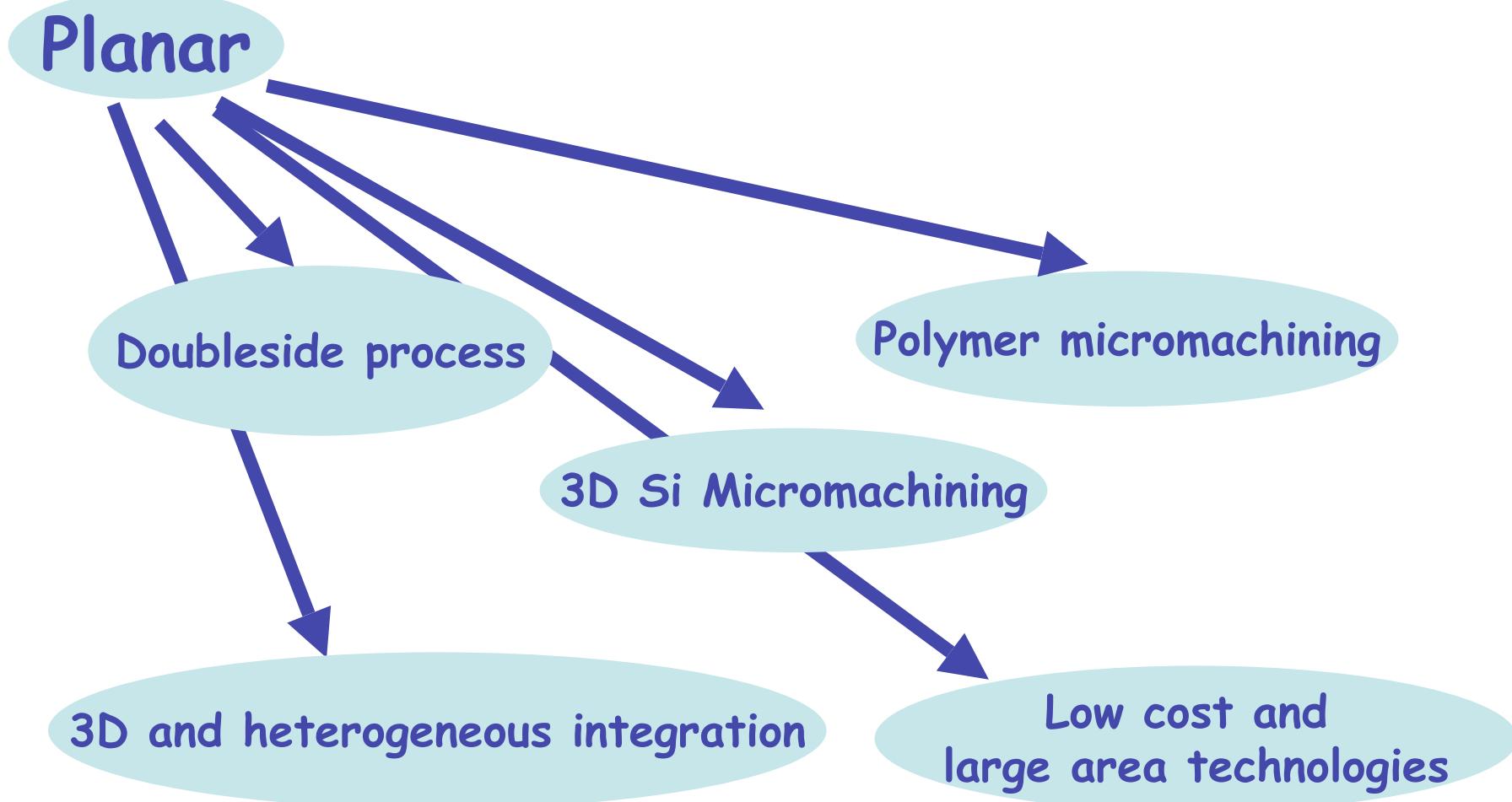


	PCB	MCM-V	3D Ultra-compact
Active volume/ total volume ratio	$25 \times 10^{-6} \%$	0.003 %	30 %
Mass (gr.)	52	7	0.5
Size (mm)	63x63x5	19.5x19x11	20x20x0.5
Volume (cm³)	20	4.7	0.2

RF Heterogeneous integration









Ink jet technology

Micro optics

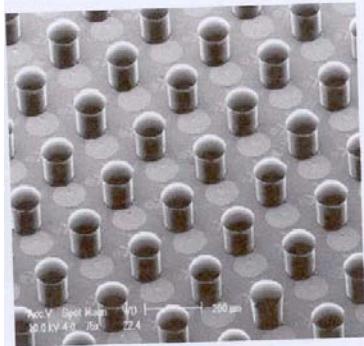


Figure 17. Wafer level fabrication of pedestals and microlenses on VCSEL wafer.

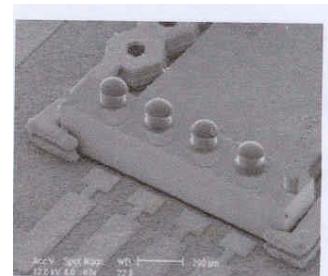


Figure 25. A lensed VCSEL die is positioned by a MEMS clamer.

(under development)

3D polymer microlenses

ink:

H_2O 30 to 50% : monitoring of viscosity and surface tension
 Photoinitiator : triarylsulfonium hexafluorophosphate ;
 Hydrolyse (3-glycidyloxypropyl trimethoxysilane) : sol gel

Wave guides

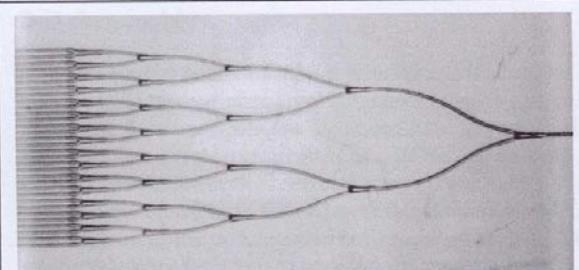


Figure 27: 25mm long, 1-to-32 branching waveguide printed using ink-jet technology.

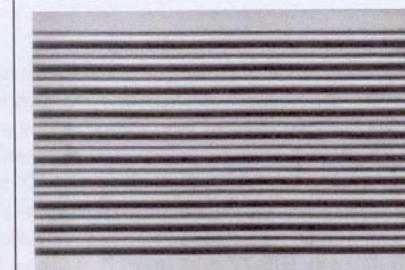


Figure 28: 125μm multi-mode waveguides printed on 150μm centers.

Results :

dimensions : Ø 50 μm to 2 mm ;
 High : 6 μm to 150μm
 Focal length : 100 μm to 2 mm
 Surface roughness: 40 nm
 indice : monitored through sol gel composition

Ink jet technology

Bumping

(under development)

Solder printing: $\varnothing 80\mu\text{m}$, high $100\mu\text{m}$

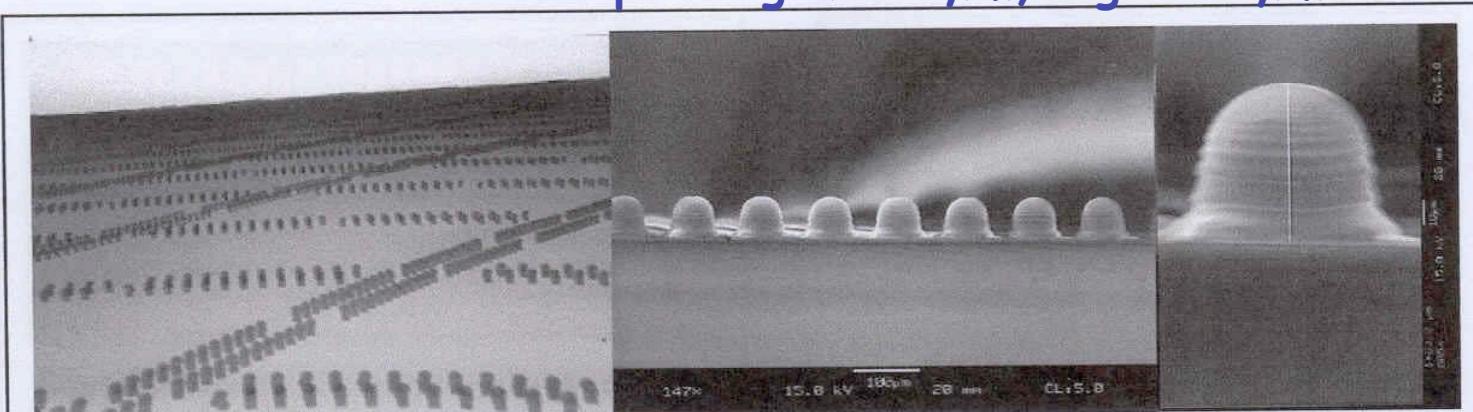
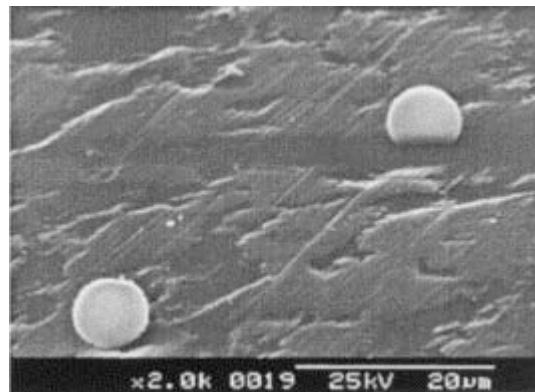


Figure 6: Wafer bumping process using Solder Jet™ equipment. Image courtesy of Dephi.



$5\mu\text{m}$ \varnothing bumps

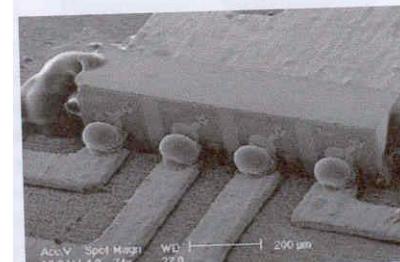
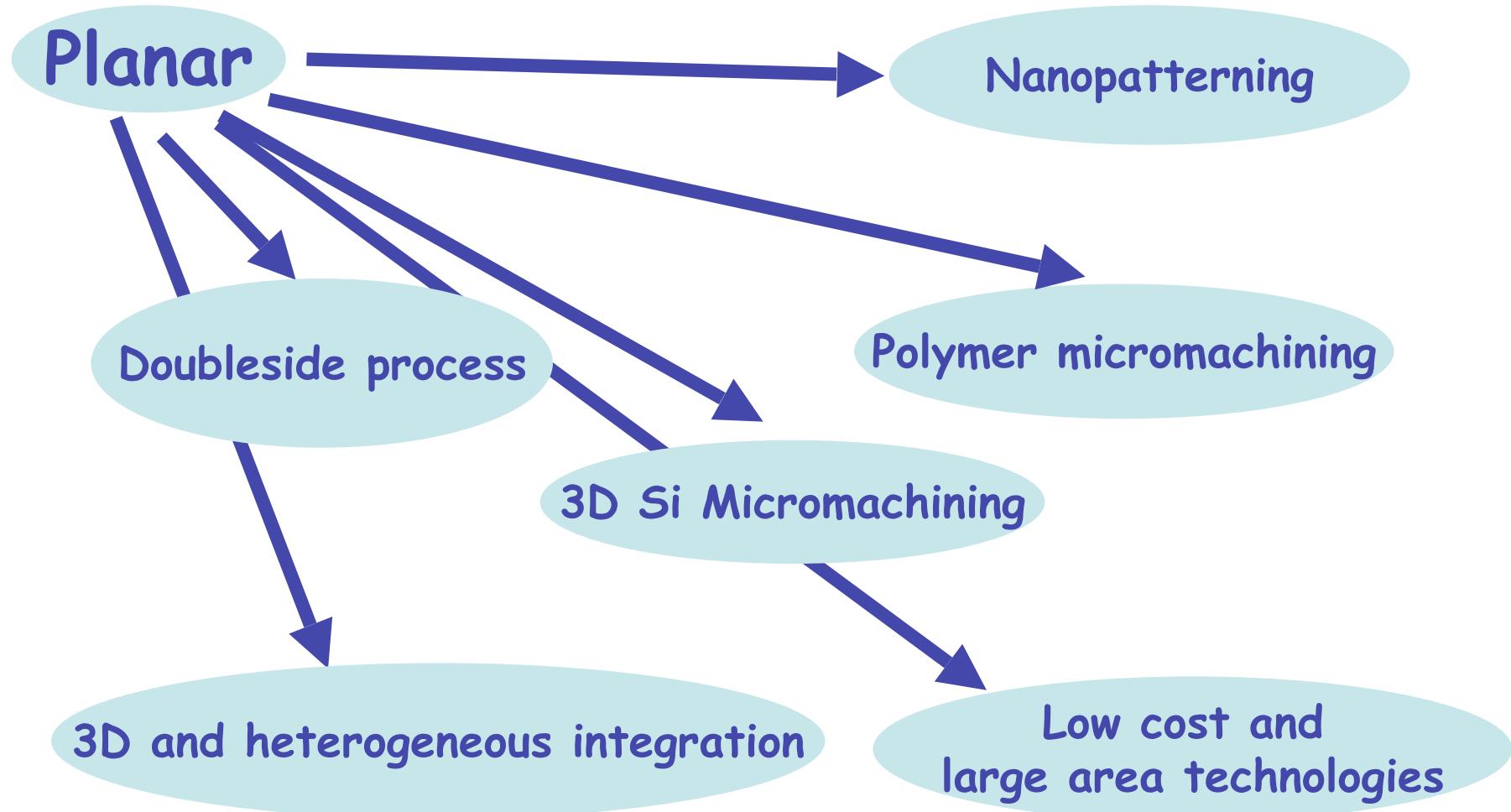


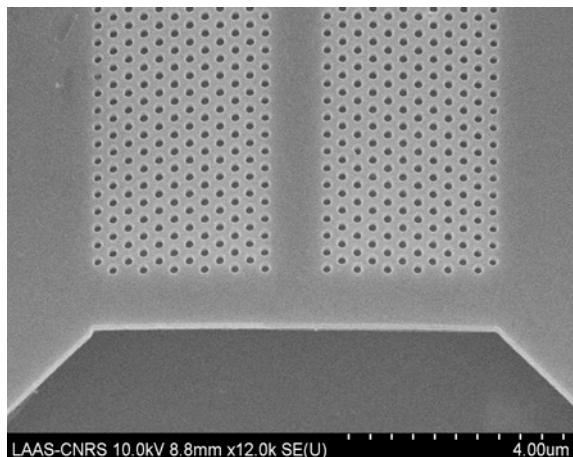
Figure 20. Direct VCSEL die bonding using SolderJet®.

Wedge bumping $\varnothing 100\mu\text{m}$

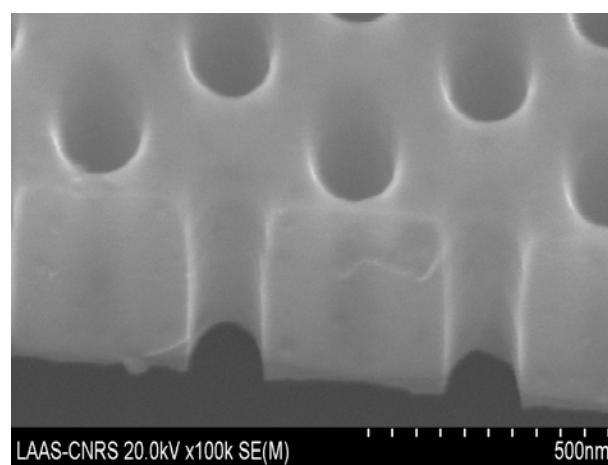




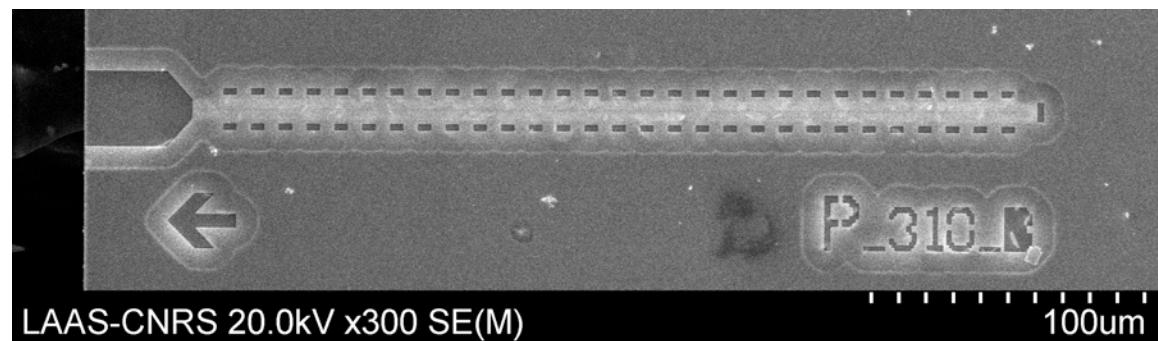
Photonic crystal lasers



*15° tilted image
of the etched mirror*



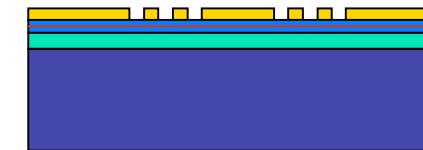
*Detail image of a cleaved edge
through the PhC holes*



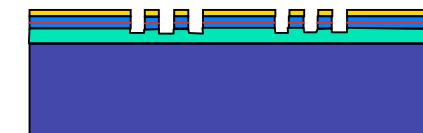
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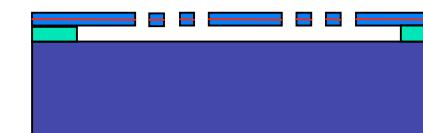
Growth (MBE (In)GaAs/AlGaAs)



*Resist spin coating
Electronic lithography*



PhC etching (ICP Cl₂/N₂)



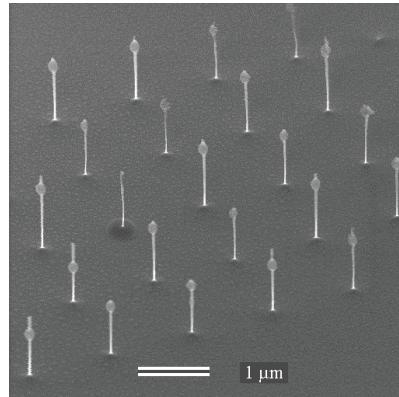
*Membrane release
(chemical etching)*



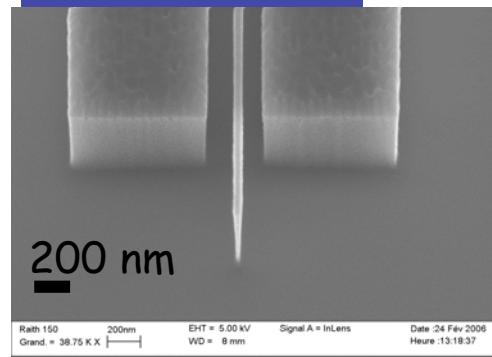
*Thinning,
cleavage*



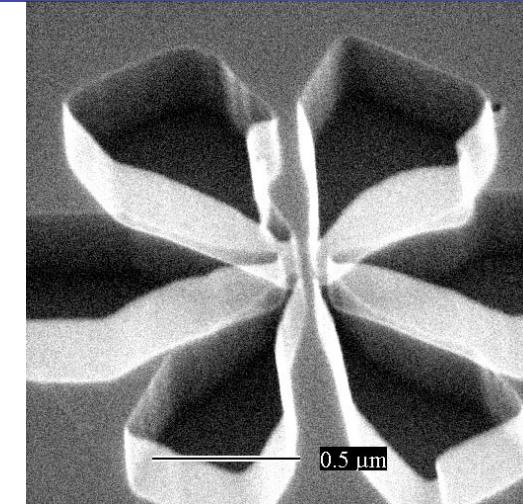
GaAs ICP nanomachining



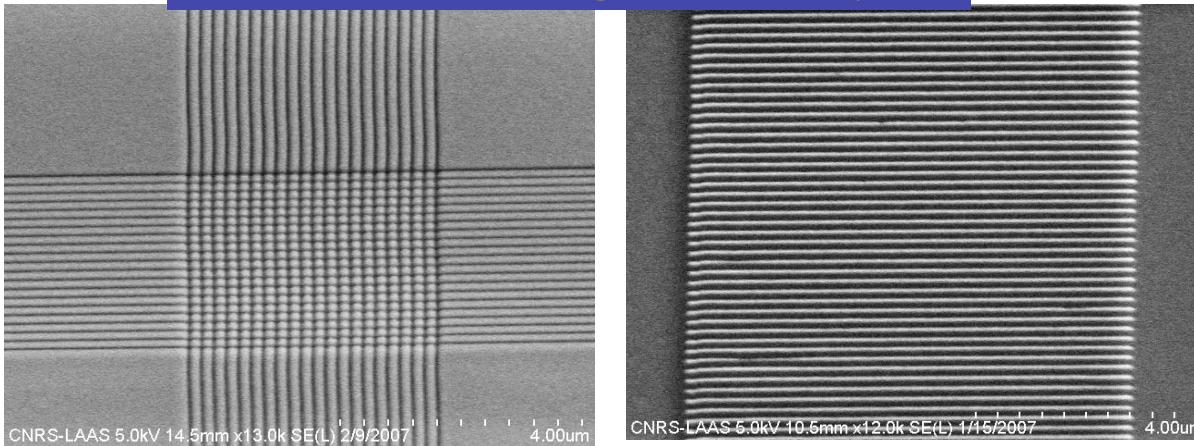
Si nanomachining



Si nanomachining for stamping



Glass micromachining for nanoimprint

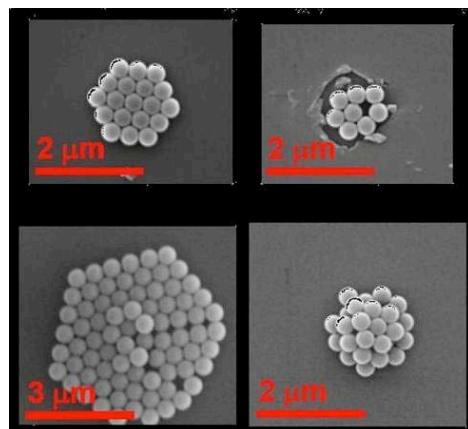
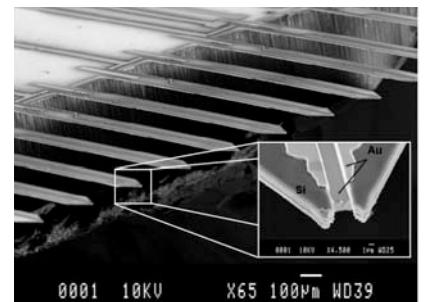


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Soft-Lithography and Self-Assembly

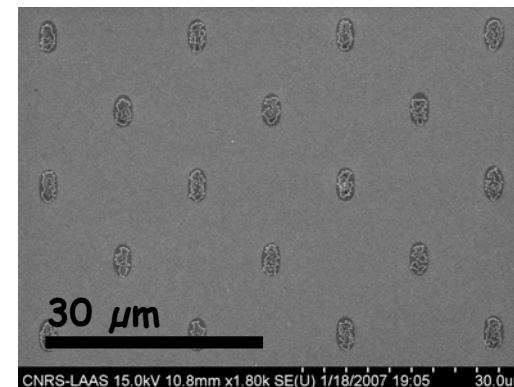
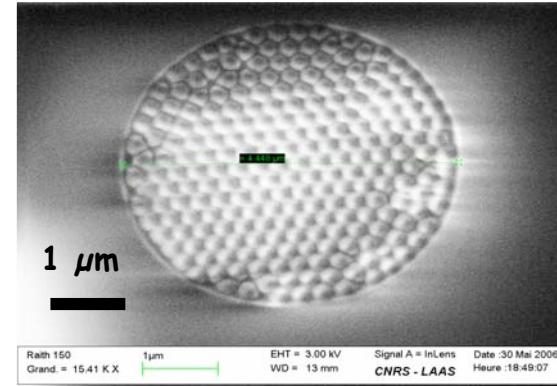
Combine top-down and Bottom-up approaches

MEMS based spotter for direct self assembly

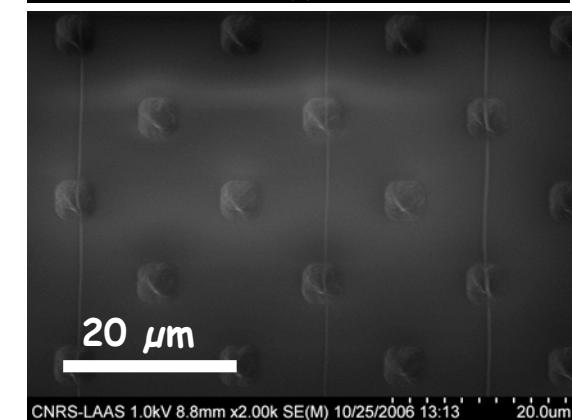
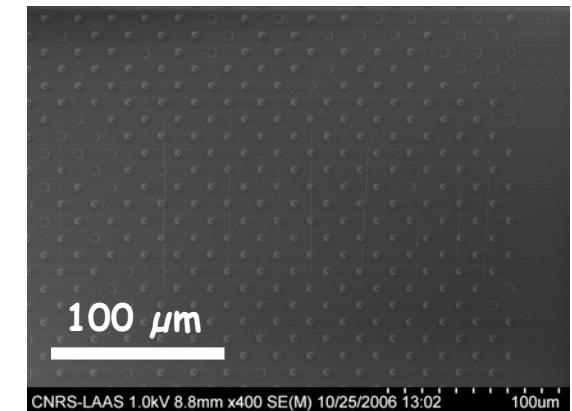


Nanobead cristal formation

Directed assembly of ordered nanoparticles on patterns



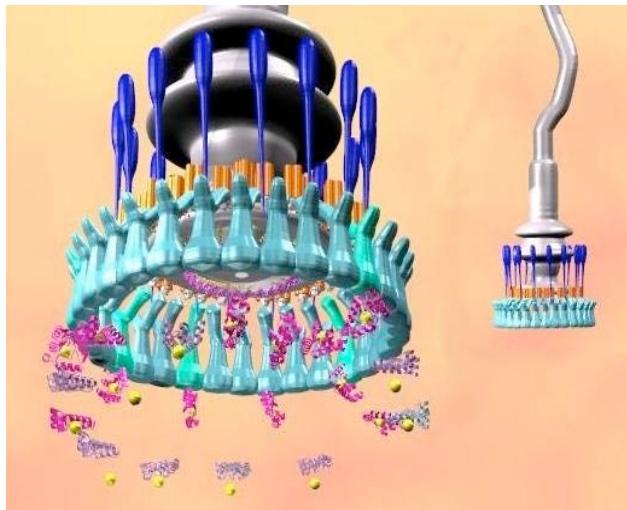
Directed assembly of DNA



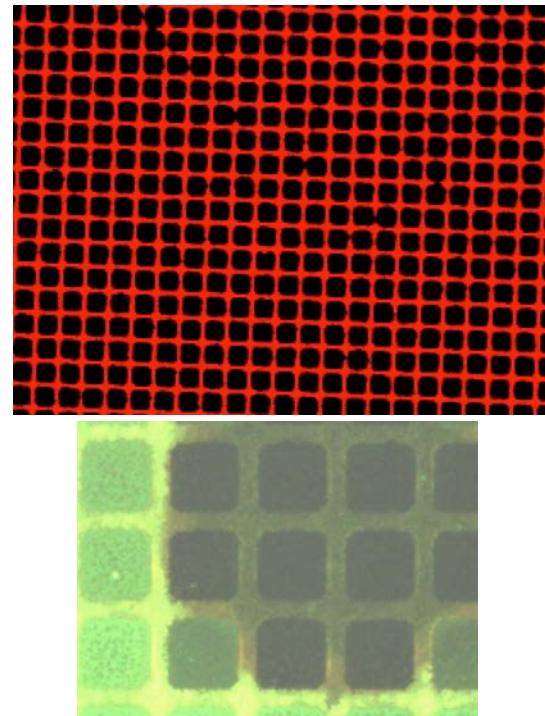


Assemble the flagellar rotary nano-motor of bacteria on a solid surface

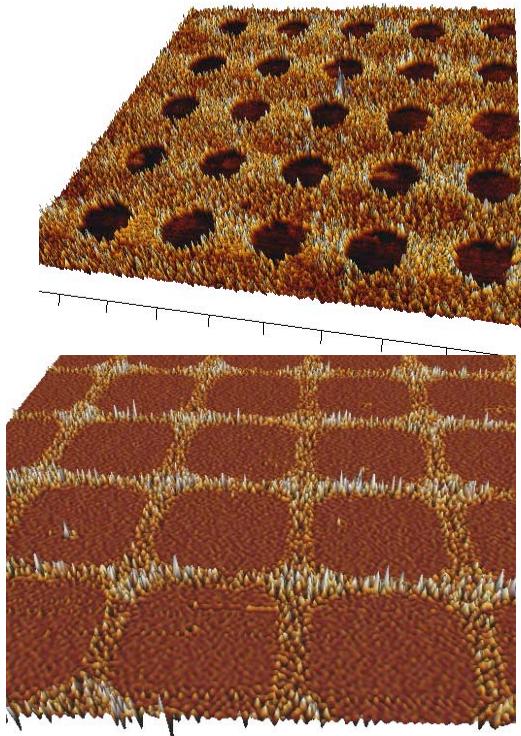
A new model for the flagellar nanomotor



Soft-Lithography and self-assembly techniques for creating nanodomains of supported lipidic membranes



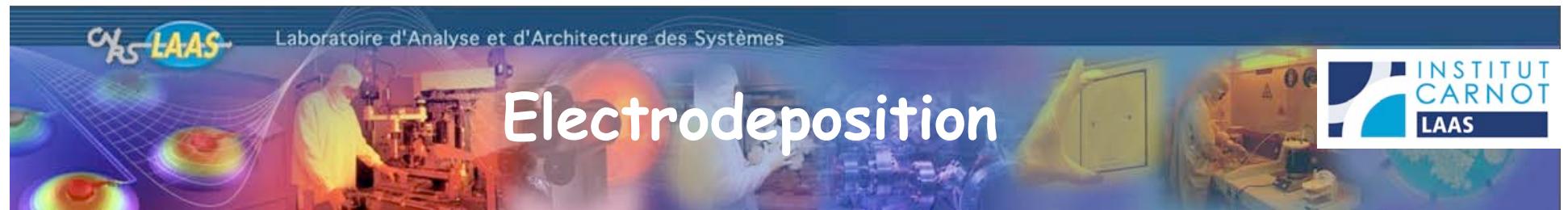
Liquid AFM imaging of the assembly process





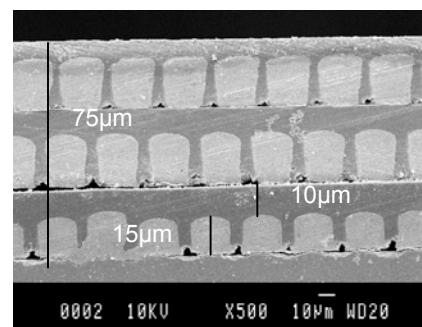
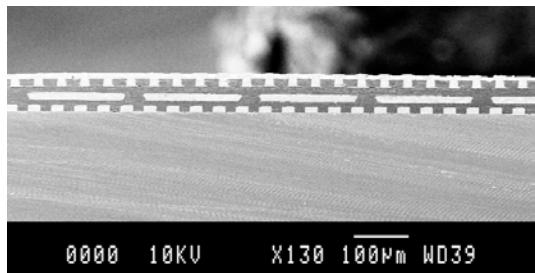
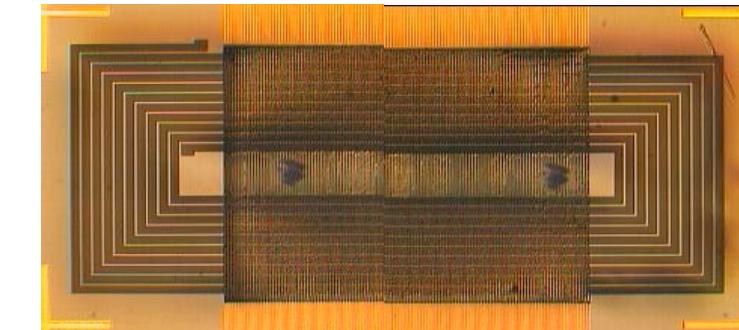
From s.c. to multimatериалs

s.c. + metal and alloys



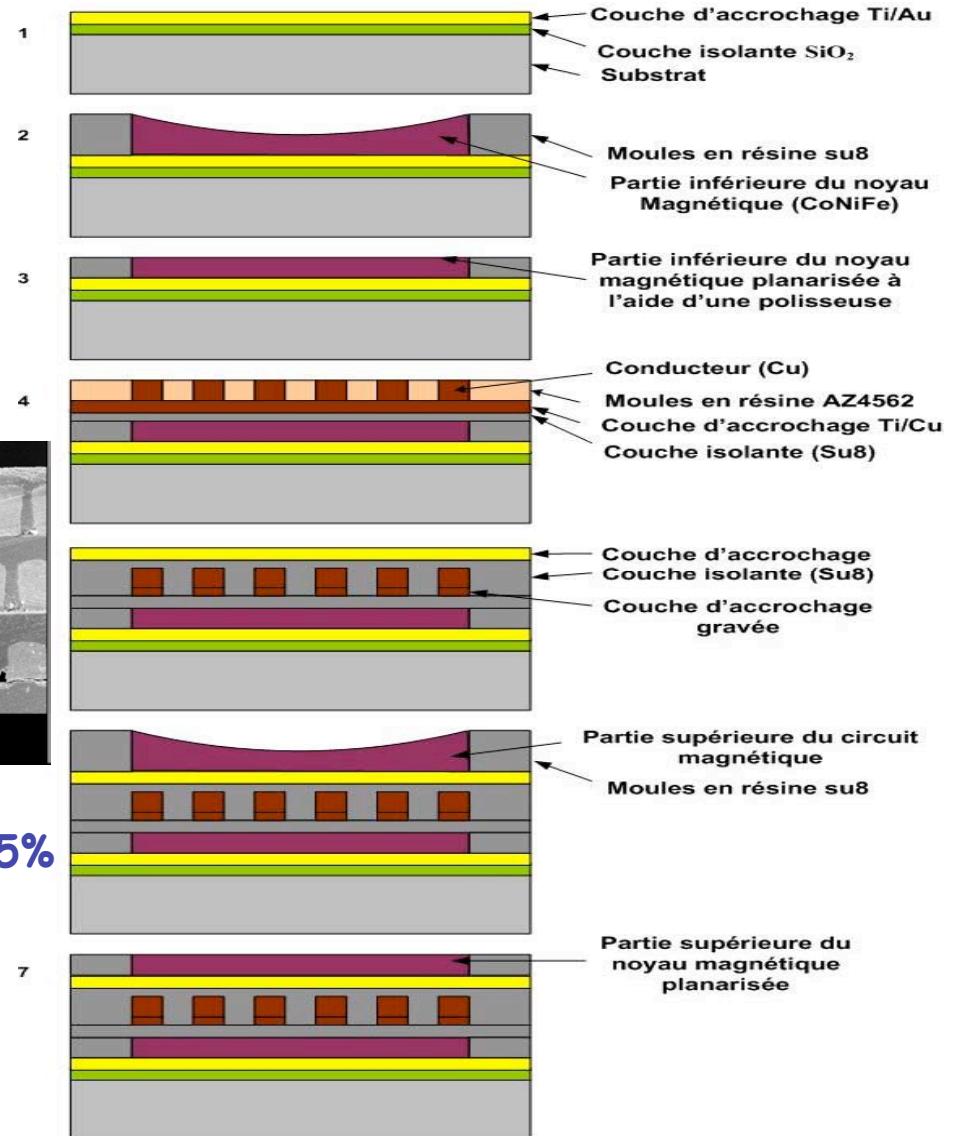
Electrodeposition

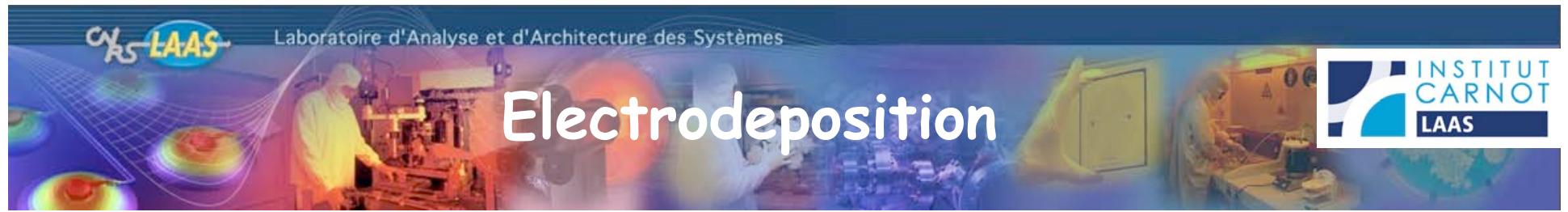
Magnetic coupling



Coil: Cu
Roughness : 20A
 $e=20\mu\text{m}$ to several hundred
Magnetic circuit: $\text{Fe}_{25}\text{Co}_{60}\text{Ni}_{15}$

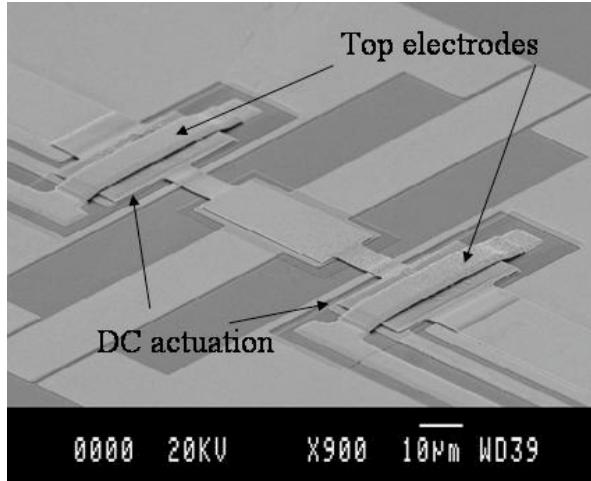
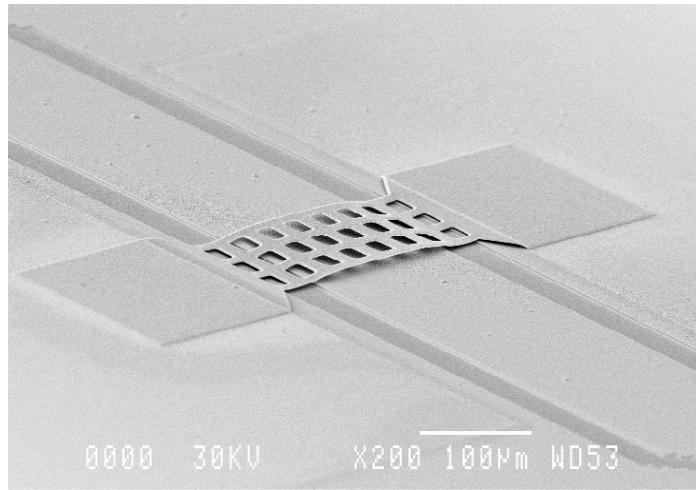
Homogeneity : 5%
Stress : 5 MPa

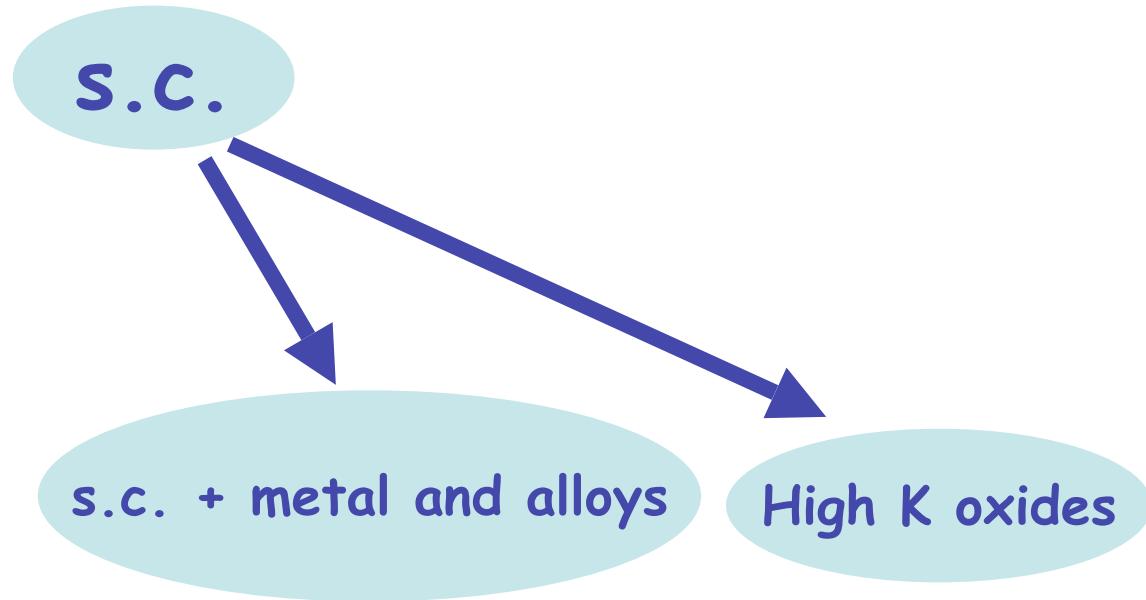




RF MEMS

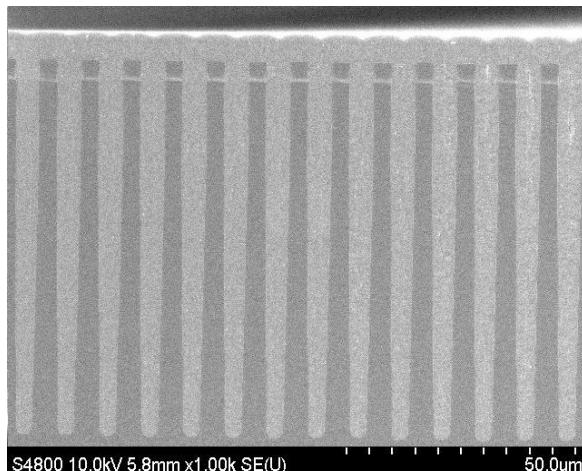
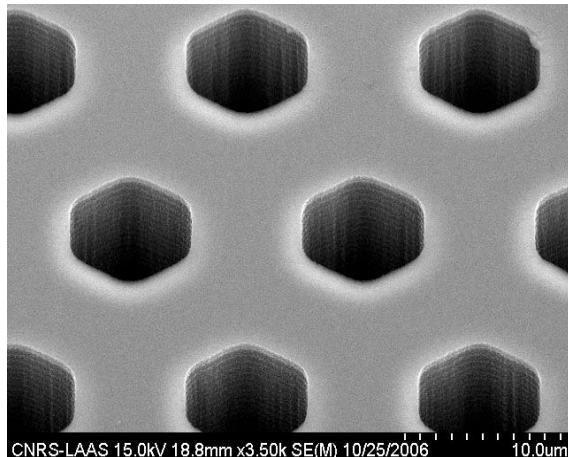
- Wafer level gold deposition
- $e = 10\mu\text{m}$
- Homogeneity : 5%
- Roughness : 20A
- Stress : 10 MPa







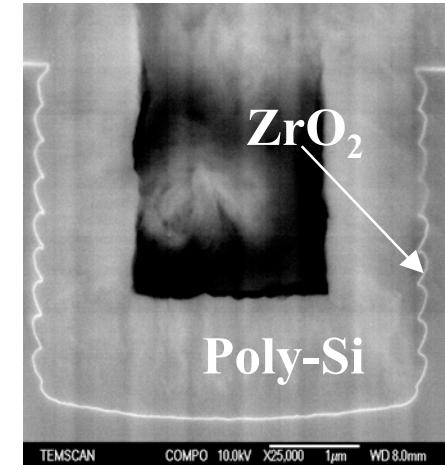
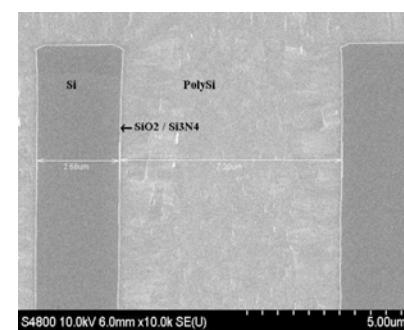
3D capacitors



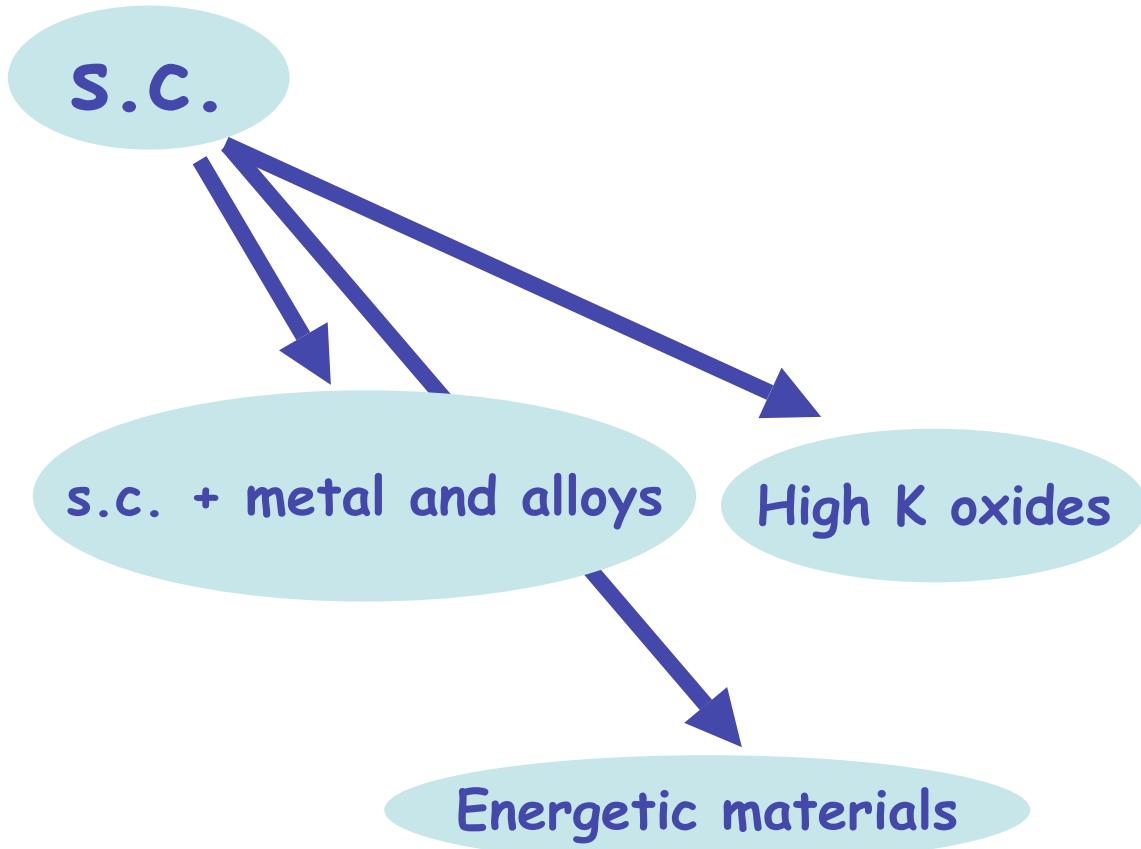
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Goal: 500 nF/mm²

- Deep silicon etching (high ratio)
- Electrochemical etching
- High K deposition in trenches

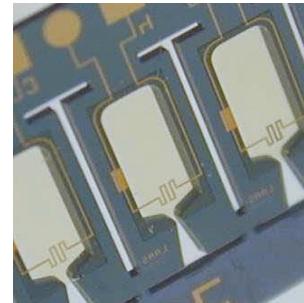
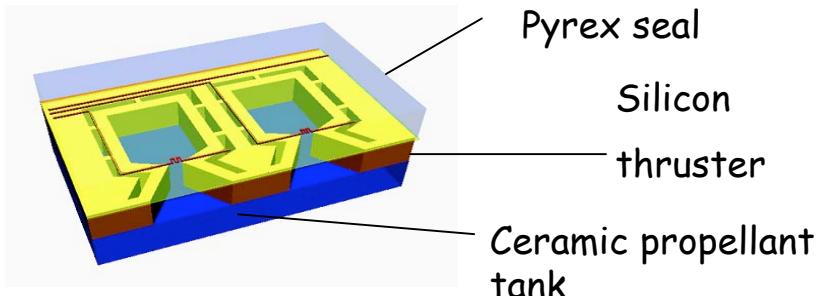


Partnership:
LAAS, INL, LEMHE, LCC



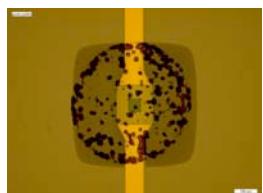
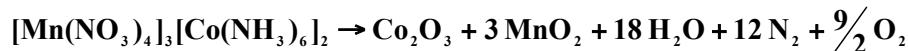
Energetic (Nano) materials for micro sources

Pyrotechnical μ thrusters



Pressure micro sources (Collaboration with LCC)

Energetic materials « gas generation » :



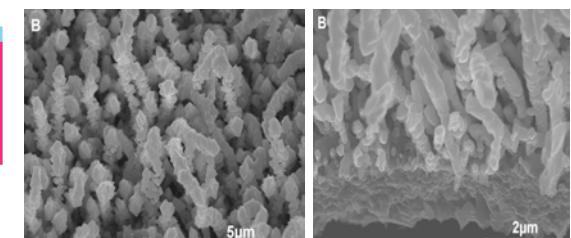
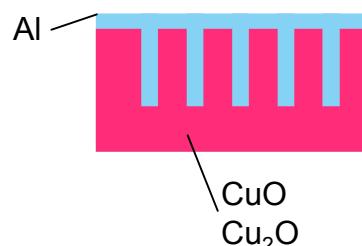
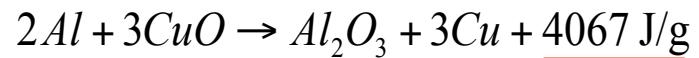
Ink jet deposition: drop $\varnothing \sim 100\mu\text{m}$
Thickness : $1.4\mu\text{m}$
Deposited mass : 195ng

Temperature: 223°C
Energy release $\Delta H = 333\text{J/g}$
gaz : $\text{N}_2, \text{O}_2, \text{H}_2\text{O}$

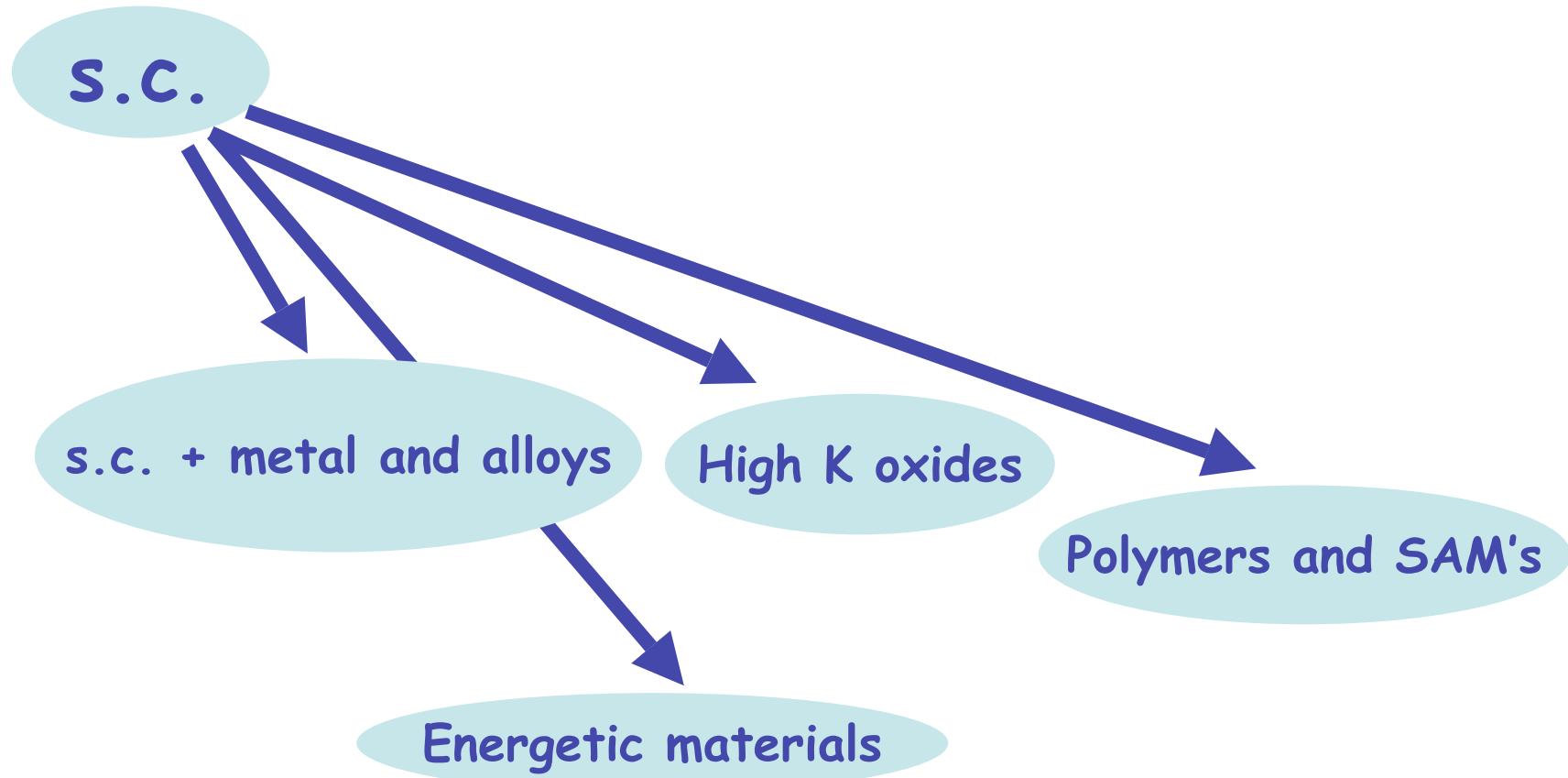
Anne-Marie Gué, 9 Novembre 2007

Heat micro sources (Collaboration with CIRIMAT)

Ex: composite Al/CuO nanostructured by Al evaporation Al on a network CuO nanowires ($\varnothing : 10\text{-}50\text{nm}$)



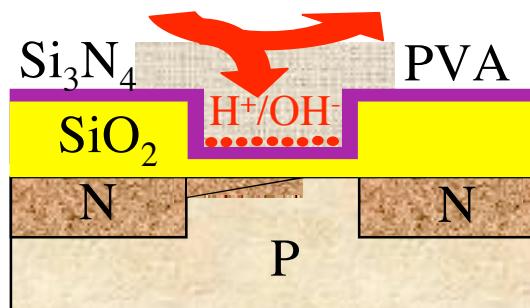
Structure and material design SEM photo : CuO/Al nanowires of 10nm as diam.



(Bio) Chemical Sensitive layers

Chemically-sensitive, photosensitive polymers using spin coating and photolithography standard techniques

enzymatic reaction



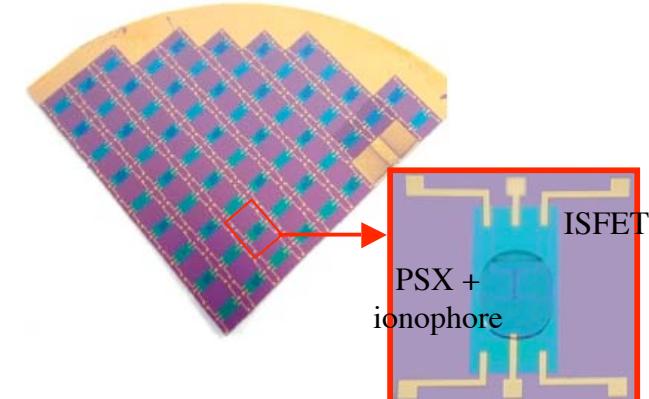
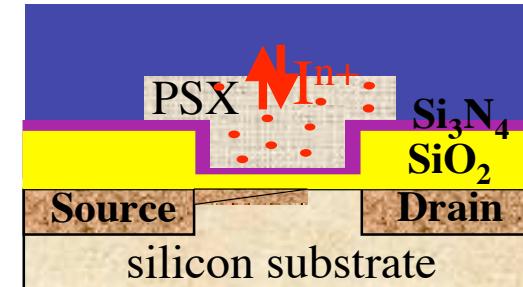
Integration of poly vinyl alcohol (PVA) based enzymatic layers on the pH-ISFET sensitive gate: realisation of EnFETs:

- Urease: $\text{CO}(\text{NH}_2)_2$ (urea) + $\text{H}_2\text{O} \longrightarrow 2\text{NH}_3 + \text{H}_2\text{CO}_3$
- Creatinine deiminase: créatinine + $\text{H}_2\text{O} \longrightarrow \text{N-methyl-hydantoïne} + \text{NH}_3$
- Others hydrolases...

Integration of ionophores using polysiloxane-based polymers: realisation of ion-sensitive layers

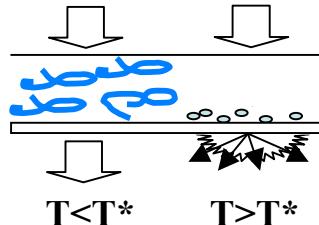
Application to standard ionophores

- Nonactin for the NH_4^+ ion detection
- Tetradodecyl ammonium nitrate (TDDAN) for the NO_3^- ion detection
- Valinomycin for the K^+ ion detection
- Monensin for the Na^+ ion detection
- ...



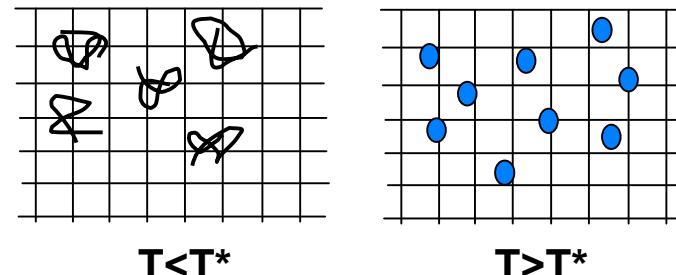
Light diffusion

PNIPAM in H₂O



0.3 s / 3s; [670-1070] nm
attenuation \approx 38 dB,
for all polarizations

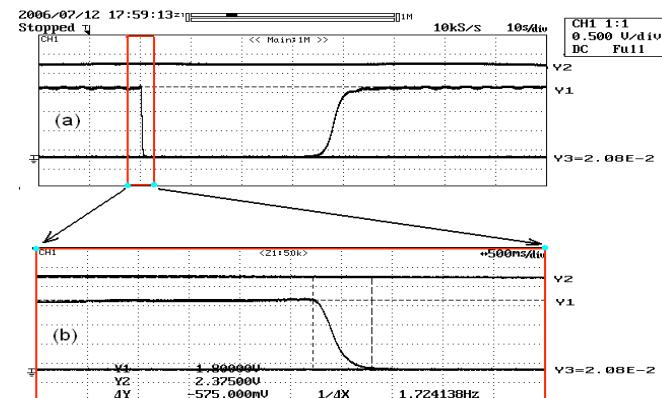
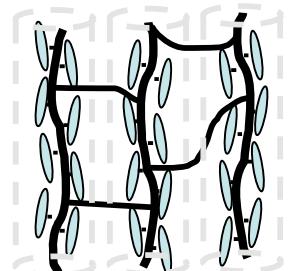
PNIPAM encapsulated in Hydro gel



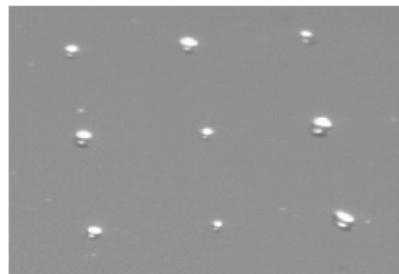
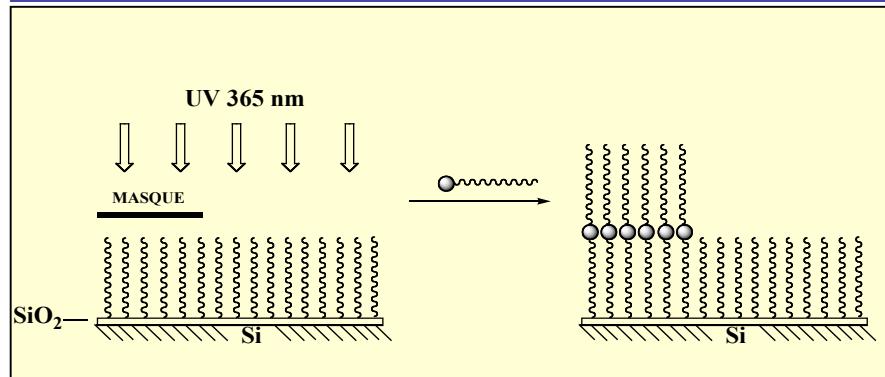
Phase modulation through thickness variation

Gel and liquid cristal : electro active

Coll. P. Keller (Inst. Curie)
L. Mager, S. Mery (GMO-IPCM, Strasbourg)



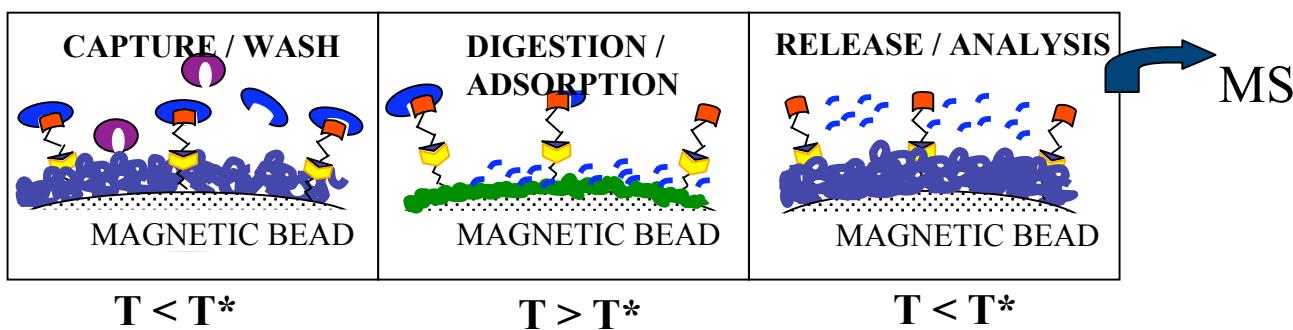
Patterning hydrophilic and hydrophobic areas using standard photolithography (365 nm)



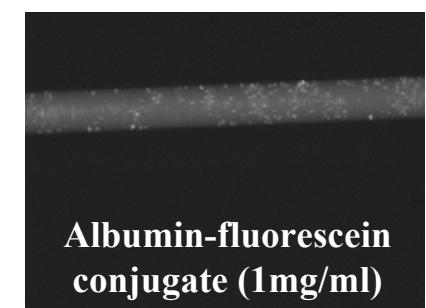
Contact Angle
 $\theta = 112^\circ$
 $\Delta\theta = 77^\circ$

Hydrophilic spots
10 to 100 μm

Stimuli responsive surface



ΔT $\updownarrow 32^\circ\text{C}$





Concluding remarks



- We are ready to take up the challenge ...
- ... but it is a huge task and almost a new job
- We need partners !!! :

material synthesis and elaboration, chemistry, surface chemistry, biochemistry, physics of fluids and interface, ...

- Many thanks to all of my colleagues
- Thank you for your attention